

In the Abstract:

Please replace the existing abstract with the following new abstract:

This invention relates to a testing method for a head IC which makes it possible to simplify checking of the head. The head IC is installed on a head suspension, and probes are placed on terminals of the head suspension to check electric characteristics of the head IC. With this invention, contact of the probes for checking the head IC when the head IC has been installed, but before installing the head, becomes easier.